

4/20/01

09/830016

532 Rec'd PCT/TO 20 APR 2001

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Yukihiro KIUCHI et al.

Serial No. (unknown)

Filed herewith

FLAME RETARDANT EPOXY RESIN
COMPOSITION AND SEMICONDUCTOR
DEVICE USING THE SAME

#2/a
10/9/02
hc

09830016-042001

PRELIMINARY AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Prior to calculation of the filing fee, please amend
the above-identified application as follows:

IN THE CLAIMS:

Amend claim 13 as follows.

—13. (amended) A semiconductor device in which

the epoxy resin composition described in claim 1 is used as a
encapsulating resin.

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